

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2853377

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	SAMSUNG TECHWIN CO., LTD.	04/30/2014
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	MDS CO., LTD.	
<b>Street Address:</b>	84, JEONGDONG-RO, SEONGSAN-GU	
<b>City:</b>	CHANGWON-SI, GYEONGSANGNAM-DO	
<b>State/Country:</b>	KOREA, REPUBLIC OF	
<b>Postal Code:</b>	641-120	
<b>PROPERTY NUMBERS Total: 14</b>		
<b>Property Type</b>	<b>Number</b>	
Application Number:	12432898	
Application Number:	13542233	
Application Number:	12475764	
Application Number:	12492382	
Application Number:	11167858	
Application Number:	11244649	
Application Number:	12328077	
Application Number:	11194285	
Application Number:	11651670	
Application Number:	11706706	
Application Number:	12156513	
Application Number:	12217195	
Application Number:	12317562	
Application Number:	12288740	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(312)569-3533	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>		
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<b>Email:</b>	Irina.Mikitiouk@dbr.com	
<b>Correspondent Name:</b>	BRIAN C. RUPP, DRINKER BIDDLE & REATH	
<b>PATENT</b>		



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ATTORNEY DOCKET NUMBER:	433774
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NAME OF SUBMITTER:	BRIAN C. RUPP
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SIGNATURE:	/brian c. rupp/
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DATE SIGNED:	05/13/2014
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**Total Attachments: 3**

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**PATENT**

Attorney Docket No. 433774

Drinker Biddle & Reath LLP  
191 N. Wacker Drive  
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Chicago, Illinois 60606-1698

**ASSIGNMENT**

**WHEREAS, SAMSUNG TECHWIN CO., LTD.**, of 28 Sungju-dong, Changwon-city, Kyongsangnam-do, Republic of Korea (hereinafter referred to as Assignor), is the owner of the Patents and Patent Applications set forth in the attached Schedule A of the inventions disclosed and claimed therein; and

**WHEREAS, MDS CO., LTD.**, of 84, Jeongdong-ro, Seongsan-gu, Changwon-si, Gyeongsangnam-do, Republic of Korea 641-120 (hereinafter referred to as Assignee), acquired the entire domestic and foreign right, title, and interest in, to and under the aforesaid patents, patent applications and inventions;

**NOW, THEREFORE**, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Assignor assigns and transfers to the Assignee and the Assignee's legal representatives, successors and assigns the entire right, title and interest in, to and under the patents, patent applications and inventions set forth in Schedule A and other such applications (e.g., continuations, continuations-in-part, divisionals, reissues, reexaminations, National phase applications, including petty patent applications, and utility model applications) that may be filed in the United States and every foreign country on the inventions, and the patents or extensions thereof, both foreign and domestic, that may issue thereon, and we do hereby authorize and request the Commissioner of Patents to issue U.S. patents to the above-mentioned Assignee agreeably with the terms of this assignment document.

**WE HEREBY AUTHORIZE** the Assignee to insert in this assignment document the filing dates and application numbers of the applications set forth in the Schedule A if the dates and numbers are unavailable at the time this document is executed.

**UPON SAID CONSIDERATION**, Assignor conveys to the Assignee the right to make application in its own behalf for protection of the invention in countries foreign to the U.S. and to claim under the Patent Cooperation Treaty, the International Convention and/or other international arrangement for any such application the date of the U.S. application (or any other application if any there be) to gain priority with respect to other applications.

**ASSIGNOR DOES HEREBY COVENANT** and agree with the Assignee that it will not execute any writing or do any act whatsoever conflicting with the terms of this assignment document set forth herein, and that Assignor will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, continuation, continuation-in-part, divisional, reexamined and reissued patent and patent applications set forth in the Schedule A or of any



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and all foreign countries on the invention, and in enforcing any rights or choses in action accruing as a result of such applications or patents, and by executing statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of all parties hereto.

IN WITNESS WHEREOF, Assignor has caused one of its officers to hereunder set his hand on the date shown below.

Date April 30, 2014

Jaesung Lee  
Signature

Jaesung Lee  
Name

IP Managing Director  
Title

Date April 30, 2014

Witness [Signature]

Date April 30, 2014

Witness [Signature]

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## SCHEDULE A

Attachment to Assignment from Samsung Techwin Co., Ltd.  
to MDS Co., Ltd.

No.	Country	Samsung Ref.:	Y.P.LEE Ref.:	DBR Ref.	Application No.	Filing Date	Patent No.	Issue Date
1	US	20071106001	SA-32373-US	P3122US	12/432,898	30/Apr/2009	8,278,564	2/Oct/2012
2	US	20071106001	SA-32373-USDIV	P3122DIV	13/542,233	5/Jul/2012		
3	US	20071109033	SA-32374-US	P3167US	12/475,764	1/Jun/2009	8,409,726	2/Apr/2013
4	US	20071204005	SA-32378-US	P3109US	12/492,382	26/Jun/2009	8,431,029	30/Apr/2013
5	US	P20040030	SA-23200-US	P2502US	11/167,858	27/Jun/2005	7,804,693	28/Sep/2010
6	US	P20040620	SA-25477-USRCE	P2544US	11/244,649	5/Oct/2005	7,470,461	12/Oct/2010
7	US	P20040620	SA-25477-USDIV	P2544DIV	12/328,077	4/Dec/2008	7,811,626	12/Oct/2010
8	US	P20050039	SA-24482-US	P2521US	11/194,285	1/Aug/2005	7,285,845	23/Oct/2007
9	US	P20050851	SA-27028-US	P2701US	11/651,670	10/Jun/2007	7,750,456	6/Jul/2010
10	US	P20050892	SA-27030-US	P2719US	11/706,706	13/Feb/2007	7,815,481	19/Oct/2010
11	US	P20070275	SA-31354-US	P2859US	12/156,513	2/Jun/2008	8,227,173	24/Jul/2012
12	US	P20070278	SA-30895-US	P2877US	12/217,195	2/Jul/2008	7,952,175	31/May/2011
13	US	P20071108	SA-32760-US	P2983US	12/317,562	23/Dec/2008	8,128,752	6/Mar/2012
14	US	P20070483	SungwooPatent	P3048US	12/288,740	23/Oct/2008	8,122,599	28/Feb/2012

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